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10/024892  
12/18/01

U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10024892	12/18/2001	438		2812	
<b>**APPLICANTS:</b> Kim Jong;					
<b>**CONTINUING DATA VERIFIED:</b>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> REPUBLIC OF KOREA 2001-47459 08/07/2001					
PG-PUB		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed		<input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no		CU-2641 VE	
Verified and Acknowledged Examiners's initials					
TITLE : Method of fabricating a wafer level package					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L(Rev. 12-94)					

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Assistant Examiner	
<b>ISSUE FEE</b>		Total Claims	
Amount Due	Date Paid	Print Claim for O.G.	
		<b>DRAWING</b>	
		Sheets Drwg.	Figs.Drwg.
		Print Fig.	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		Primary Examiner	
		Application Examiner	
		<b>PREPARED FOR ISSUE</b>	
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